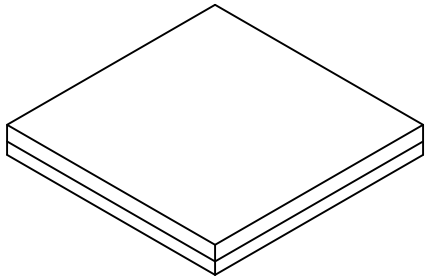
HMCCA,01/24/00,10:30:18,PBGA,2D101,J6-01 RGUER,08/28/00,11:22:09,HP517Q

REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	N/A	INITIAL ENGINEERING REVIEW	HOCHOI	HOCHOI	09/22/03
01	N/A	CHANGED BALL SIZE FROM 0.27 TO 0.25 PER REQ.	HOCHOI	HOCHOI	10/02/03



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 100.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10X10.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.40mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030

ANGULAR ±1°

INTERPRET DIM AND TOL PER ASME Y14.5M - 1994

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED HOCHOI	08/07/03
CHECKED MJLEE	08/07/03
PRODUCT MANAGER TPANC	08/07/03
RELEASED JDKIM	09/22/03

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - MAF, 10X 10 MATRIX, 5.00mm X 5.00mm X 0.85mm, 0.45mm MOLD CAP, 0.25mm BALL, 0.40mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	302877	01

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 3

FORM NO: MBFLAM1C1.DWG